Preferred Device

# **General Purpose Transistors**

### **PNP Silicon**

#### **Features**

• Pb-Free Packages are Available\*

#### **MAXIMUM RATINGS**

| Rating   | Symbol  | Value       | Unit        |
|--|---|-------------|-------------|
| Collector – Emitter Voltage  | V <sub>CEO</sub>                              | -60         | Vdc         |
| Collector - Base Voltage   | $V_{CBO}$                                     | -60         | Vdc         |
| Emitter – Base Voltage   | V <sub>EBO</sub>                              | -5.0        | Vdc         |
| Collector Current – Continuous                                       | etor Current – Continuous I <sub>C</sub> –600 |             | mAdc        |
| Total Device Dissipation  @ T <sub>A</sub> = 25°C  Derate above 25°C | P <sub>D</sub>                                | 625<br>5.0  | mW<br>mW/°C |
| Total Device Dissipation  @ T <sub>C</sub> = 25°C  Derate above 25°C | P <sub>D</sub>                                | 1.5<br>12   | W<br>mW/°C  |
| Operating and Storage Junction<br>Temperature Range                  | T <sub>J</sub> , T <sub>stg</sub>             | -55 to +150 | °C          |

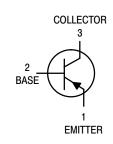
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

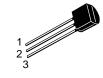
#### THERMAL CHARACTERISTICS

| Characteristic                             | Symbol          | Max  | Unit |
|--|-----------------|------|------|
| Thermal Resistance,<br>Junction–to–Ambient | $R_{\theta JA}$ | 200  | °C/W |
| Thermal Resistance, Junction-to-Case       | $R_{\theta JC}$ | 83.3 | °C/W |



# http://onsemi.com





TO-92 CASE 29 STYLE 1

#### MARKING DIAGRAM



MPS2 = Device Code

907A = Specific Device Code A Assembly Location

Y = Year WW = Work Week

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### FI FCTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

| Characteristic   |  |                      | Min                           | Max                     | Unit |
|--|--|----------------------|-------------------------------|-------------------------|------|
| OFF CHARACTERISTICS  |  |                      |                               |                         |      |
| Collector – Emitter Breakdown Voltage (Note 1) (I <sub>C</sub> = –10 mAdc, I <sub>B</sub> = 0)   |  |                      | -60                           | -                       | Vdc  |
| Collector – Base Breakdown Voltage (I <sub>C</sub> =   | –10 μAdc, I <sub>E</sub> = 0)                            | V <sub>(BR)CBO</sub> | -60                           | -                       | Vdc  |
| Emitter-Base Breakdown Voltage (I <sub>E</sub> = -1  | $I0$ μAdc, $I_C = 0$ )                                   | V <sub>(BR)EBO</sub> | -5.0                          | _                       | Vdc  |
| Collector Cutoff Current (V <sub>CE</sub> = −30 Vdc, \   | $V_{EB(off)} = -0.5 \text{ Vdc}$                         | I <sub>CEX</sub>     | -                             | -50                     | nAdc |
| Collector Cutoff Current $(V_{CB} = -50 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -50 \text{ Vdc}, I_E = 0, T_A = 150^{\circ}\text{C})$  |  |                      |                               | -0.01<br>-10            | μAdc |
| Base Current ( $V_{CE} = -30 \text{ Vdc}, V_{EB(off)} = -$   | 0.5 Vdc)   | I <sub>B</sub>       | -                             | -50                     | nAdc |
| ON CHARACTERISTICS   |  |                      |                               |                         |      |
| DC Current Gain $ \begin{aligned} &(I_C = -0.1 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ &(I_C = -1.0 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ &(I_C = -10 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ &(I_C = -10 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ &(I_C = -150 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \text{ (Note 1)} \\ &(I_C = -500 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \text{ (Note 1)} \end{aligned} $ |  | h <sub>FE</sub>      | 75<br>100<br>100<br>100<br>50 | -<br>-<br>-<br>300<br>- | _    |
| Collector – Emitter Saturation Voltage (Note 1)<br>( $I_C = -150 \text{ mAdc}$ , $I_B = -15 \text{ mAdc}$ )<br>( $I_C = -500 \text{ mAdc}$ , $I_B = -50 \text{ mAdc}$ )  |  | V <sub>CE(sat)</sub> |                               | -0.4<br>-1.6            | Vdc  |
| Base – Emitter Saturation Voltage (Note 1)<br>( $I_C = -150$ mAdc, $I_B = -15$ mAdc)<br>( $I_C = -500$ mAdc, $I_B = -50$ mAdc)   |  |                      | -<br>-                        | -1.3<br>-2.6            | Vdc  |
| SMALL-SIGNAL CHARACTERISTICS   |  |                      |                               |                         |      |
| Current – Gain – Bandwidth Product (Notes 1 and 2),<br>(I <sub>C</sub> = –50 mAdc, V <sub>CE</sub> = –20 Vdc, f = 100 MHz)   |  | fτ                   | 200                           | -                       | MHz  |
| Output Capacitance (V <sub>CB</sub> = -10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)  |  |                      | -                             | 8.0                     | pF   |
| Input Capacitance (V <sub>EB</sub> = -2.0 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)  |  | C <sub>ibo</sub>     | -                             | 30                      | pF   |
| SWITCHING CHARACTERISTICS  |  |                      |                               |                         |      |
| Turn-On Time   | $(V_{CC} = -30 \text{ Vdc}, I_{C} = -150 \text{ mAdc},$  | t <sub>on</sub>      | -                             | 45                      | ns   |
| Delay Time   | $I_{B1} = -15 \text{ mAdc}$ ) (Figures 1 and 5)          | t <sub>d</sub>       | -                             | 10                      | ns   |
| Rise Time  |  | t <sub>r</sub>       | -                             | 40                      | ns   |
| Turn-Off Time  | $(V_{CC} = -6.0 \text{ Vdc}, I_{C} = -150 \text{ mAdc},$ | t <sub>off</sub>     | -                             | 100                     | ns   |
| Storage Time   | $I_{B1} = I_{B2} = 15 \text{ mAdc}$ ) (Figure 2)         | t <sub>s</sub>       | _                             | 80                      | ns   |

Fall Time

1. Pulse Test: Pulse Width  $\leq 300~\mu s$ , Duty Cycle  $\leq 2\%$ . 2. f<sub>T</sub> is defined as the frequency at which  $|h_{fe}|$  extrapolates to unity.

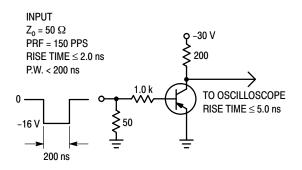
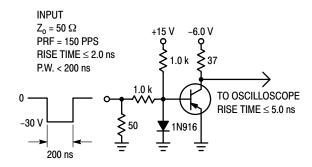


Figure 1. Delay and Rise Time Test Circuit



 $t_f$ 

30

Figure 2. Storage and Fall Time Test Circuit

#### **ORDERING INFORMATION**

| Device        | Package            | Shipping <sup>†</sup> |
|---------------|--------------------|-----------------------|
| MPS2907A      | TO-92              | 5000 Units / Box      |
| MPS2907AG     | TO-92<br>(Pb-Free) | 5000 Units / Box      |
| MPS2907ARL    | TO-92              | 2000 / Tape & Reel    |
| MPS2907ARLG   | TO-92<br>(Pb-Free) | 2000 / Tape & Reel    |
| MPS2907ARL1G  | TO-92              | 2000 / Tape & Reel    |
| MPS2907ARL1G  | TO-92<br>(Pb-Free) | 2000 / Tape & Reel    |
| MPS2907ARLRA  | TO-92              | 2000 / Tape & Reel    |
| MPS2907ARLRAG | TO-92<br>(Pb-Free) | 2000 / Tape & Reel    |
| MPS2907ARLRE  | TO-92              | 2000 / Ammo Pack      |
| MPS2907ARLREG | TO-92<br>(Pb-Free) | 2000 / Ammo Pack      |
| MPS2907ARLRM  | TO-92              | 2000 / Ammo Pack      |
| MPS2907ARLRP  | TO-92              | 2000 / Ammo Pack      |
| MPS2907ARLRPG | TO-92<br>(Pb-Free) | 2000 / Ammo Pack      |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **TYPICAL CHARACTERISTICS**

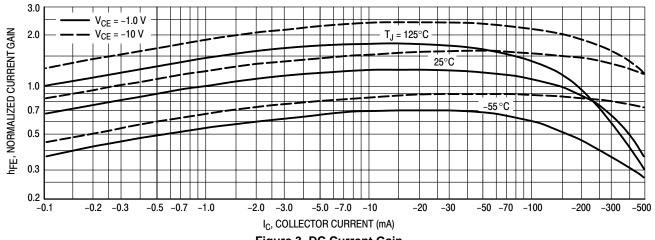


Figure 3. DC Current Gain

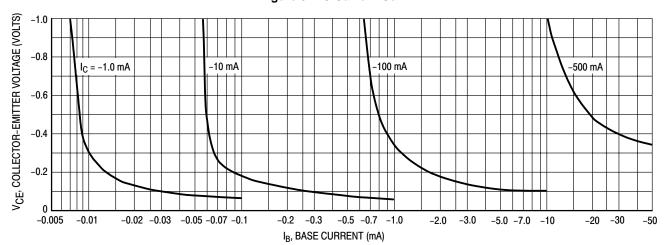
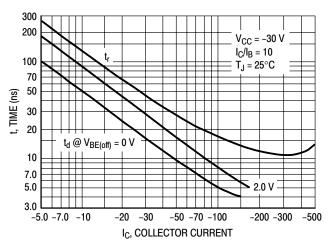


Figure 4. Collector Saturation Region

#### **TYPICAL CHARACTERISTICS**



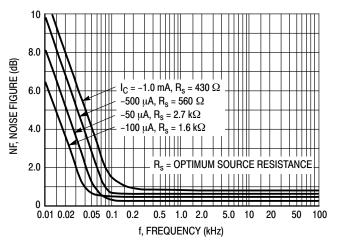
500 300  $V_{CC} = -30 \text{ V}$  $I_C/I_B = 10$ 200  $\mathsf{I}_{\mathsf{B}1} = \mathsf{I}_{\mathsf{B}2}$  $T_J = 25^{\circ}C$ 100 t, TIME (ns) 70 50  $t_s' = t_s - 1/8 t_f$ 30 20 10 7.0 -5.0 -7.0 -10 -50 -70 IC, COLLECTOR CURRENT (mA)

Figure 5. Turn-On Time

Figure 6. Turn-Off Time

# TYPICAL SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

 $V_{CE} = 10 \text{ Vdc}, T_A = 25^{\circ}\text{C}$ 





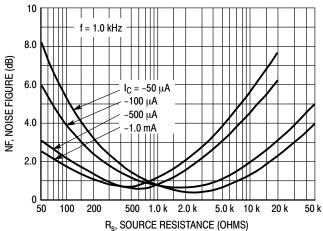
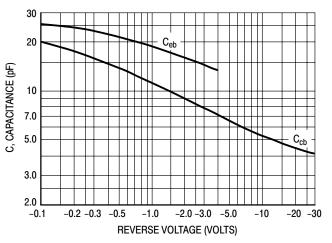


Figure 8. Source Resistance Effects

#### TYPICAL SMALL-SIGNAL CHARACTERISTICS

**NOISE FIGURE** 

 $V_{CE} = 10 \text{ Vdc}, T_A = 25^{\circ}\text{C}$ 



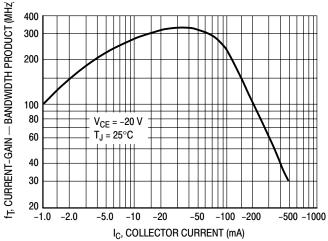


Figure 9. Capacitances

Figure 10. Current-Gain — Bandwidth Product

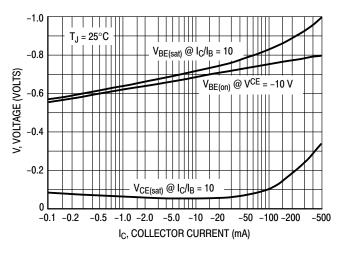


Figure 11. "On" Voltage

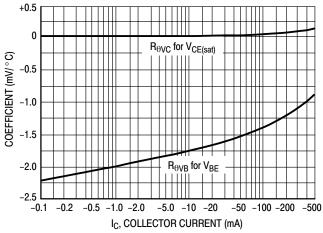
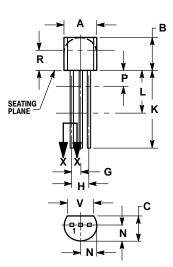
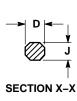


Figure 12. Temperature Coefficients

#### PACKAGE DIMENSIONS

TO-92 TO-226AA CASE 29-11 **ISSUE AL** 





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
  CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

|     | INCHES |       | MILLIN | IETERS |
|-----|--------|-------|--------|--------|
| DIM | MIN    | MAX   | MIN    | MAX    |
| Α   | 0.175  | 0.205 | 4.45   | 5.20   |
| В   | 0.170  | 0.210 | 4.32   | 5.33   |
| С   | 0.125  | 0.165 | 3.18   | 4.19   |
| D   | 0.016  | 0.021 | 0.407  | 0.533  |
| G   | 0.045  | 0.055 | 1.15   | 1.39   |
| Н   | 0.095  | 0.105 | 2.42   | 2.66   |
| J   | 0.015  | 0.020 | 0.39   | 0.50   |
| K   | 0.500  |       | 12.70  |        |
| L   | 0.250  |       | 6.35   |        |
| N   | 0.080  | 0.105 | 2.04   | 2.66   |
| P   |        | 0.100 |        | 2.54   |
| R   | 0.115  |       | 2.93   |        |
| ٧   | 0.135  |       | 3.43   |        |

STYLE 1:

PIN 1. EMITTER

2 BASE

3. COLLECTOR

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